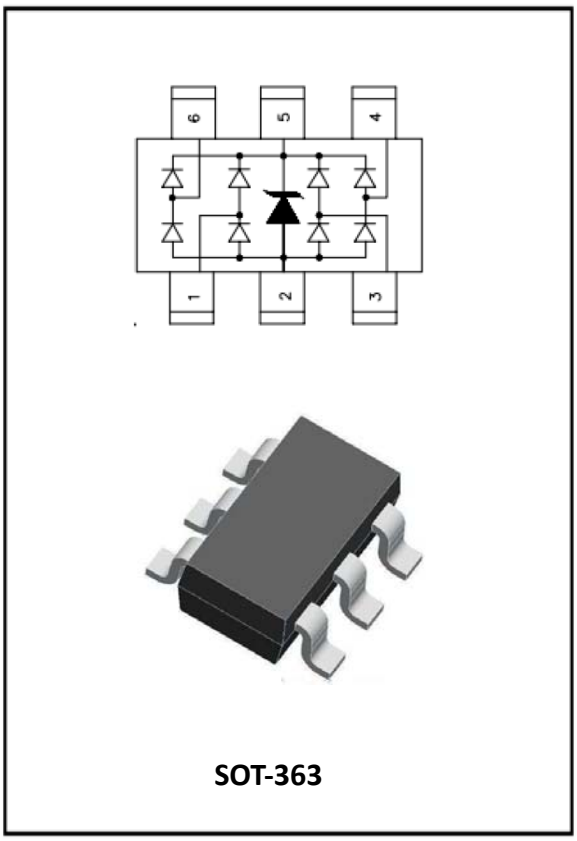
4-Line, Uni-directional, Ultra-low Capacitance, Transient Voltage Suppressor



Features

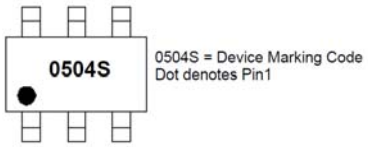
- Stand-off voltage: 5V Max
- Transient protection for each line according to
  IEC61000-4-2(ESD): ±20kV (contact)
  IEC61000-4-5(surge): 5A (8/20μs)
- Ultra low capacitance: 0.3pF typical (I/O to I/O)
- Ultra low leakage: nA level
- Low clamping voltage:
- RoHS Compliant

Applications

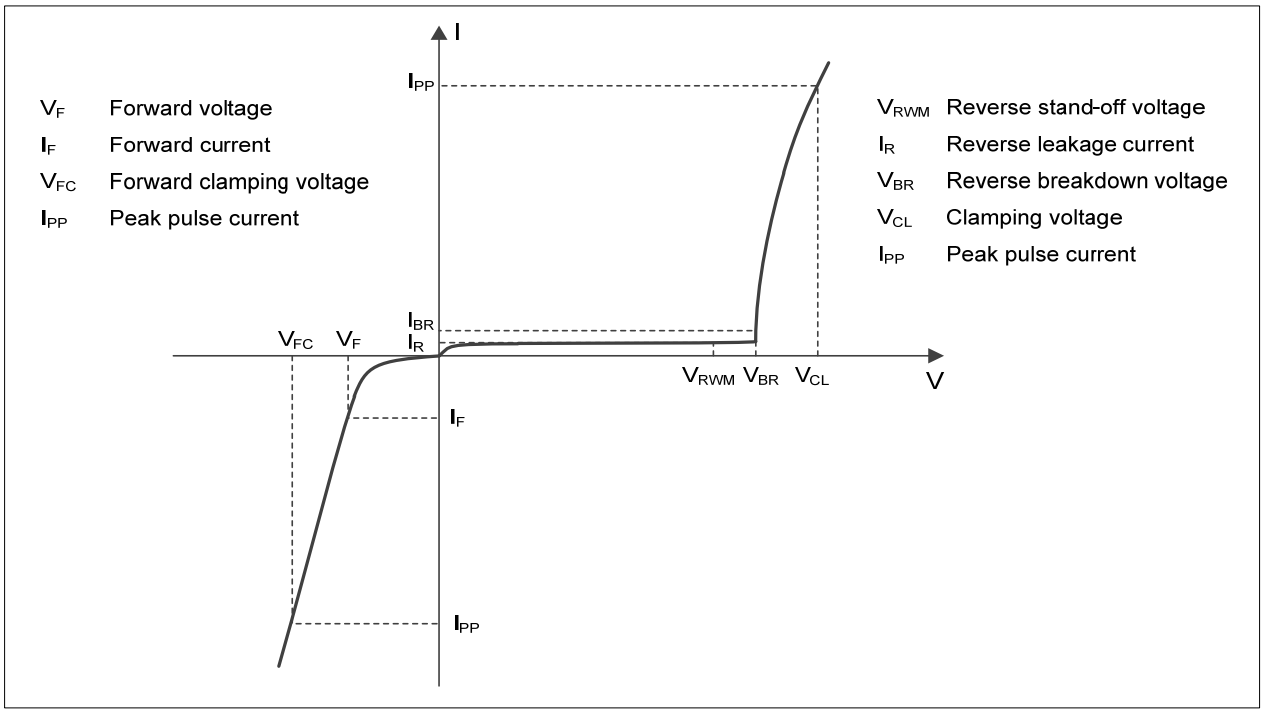
- USB 2.0 and USB 3.0 Ports
- USB OTG
- Digital Visual Interface (DVI)
- Monitor and Flat Panel Displays
- PCI Express and Serial SATA Ports
- Gigabit Ethernet
- IEEE 1394 Firewire Ports
- Consumer products (STB, DVD, DSC, DVC...)

Mechanical Data

- Package: SOT-363
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound
- Moisture Sensitivity: Level 1 per J-STD-020
- Marking Information: See Below



■Definitions of electrical characteristics



■Maximum Ratings

PARAMETER	SYMBOL	LIMITS	UNIT
Peak pulse power (t_p = 8/20μs)	P_{pk}	75	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±25	KV
ESD according to IEC61000-4-2 contact discharge		±20	
Junction temperature	T_J	-55~125	℃
Storage temperature	T_{STG}	-55~150	℃

■Electrical Characteristics（T_a=25℃ Unless otherwise specified）

PARAMETER	Symbol	UNIT	Conditions	Min	Typ	Max
Reverse maximum working voltage	V_{RWM}	V	Any I/O pin to ground			5
Reverse leakage current	I_R	μA	V_{RWM} = 5V, any I/O pin to ground			0.5
Reverse breakdown voltage	V_{BR}	V	I_T = 1mA, any I/O pin to ground	6.0		
Clamping voltage	V_{CL}	V	I_{PP} = 1A, t_p = 8/20μs, any I/O pin to ground			10
		V	I_{PP} = 5A, t_p = 8/20μs, any I/O pin to ground			15
Junction capacitance	CJ	pF	V_R = 0V, f = 1MHz, Any I/O pin to GND			0.8
			V_R = 0V, f = 1MHz, Between any I/O pin		0.3	0.4

Note: I/O pins are Pin 1, 3, 4 and 6

■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(mg)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
ESDSLC0504S3	F2	Approximate 9	3000	30000	120000	7 reel

■ Characteristics (Typical)

Fig.1 8/20μs waveform per IEC61000-4-5

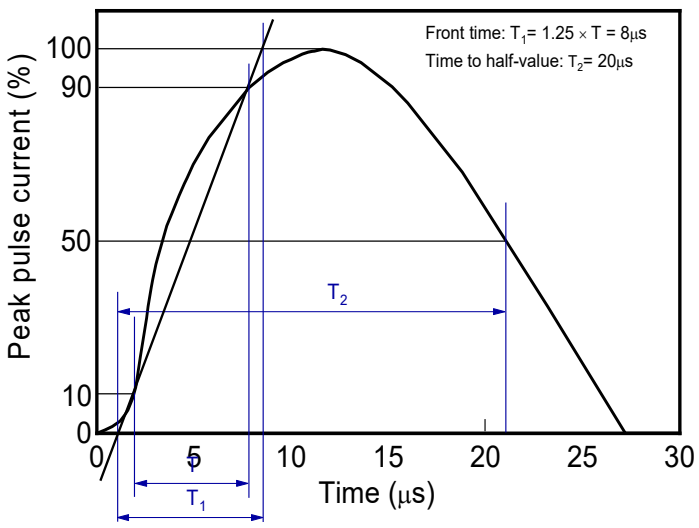


Fig.2 Contact discharge current waveform per IEC61000-4-2

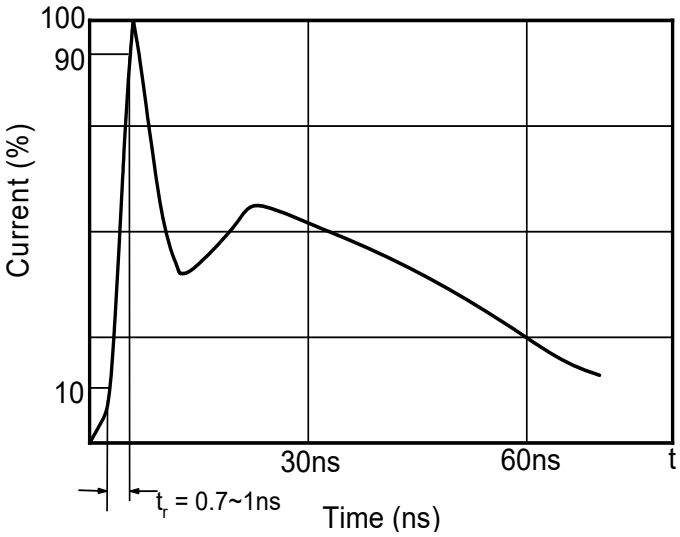


Fig.3 Clamping voltage vs. Peak pulse current

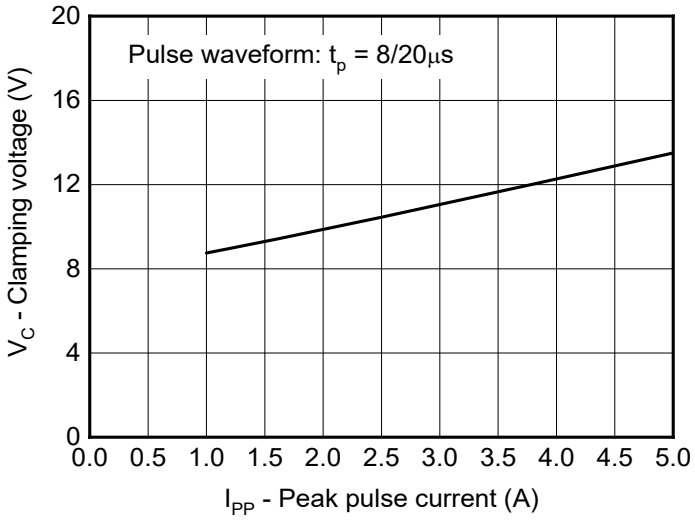


Fig.4 Capacitance vs. Reverse voltage

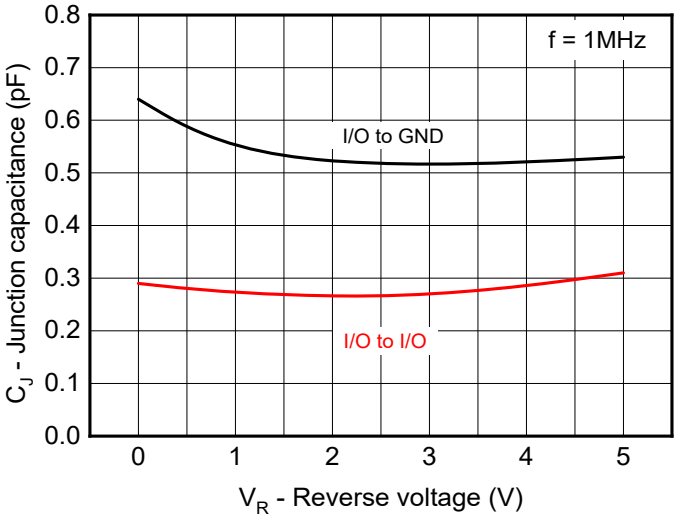


Fig.5 Non-repetitive peak pulse power vs. Pulse time

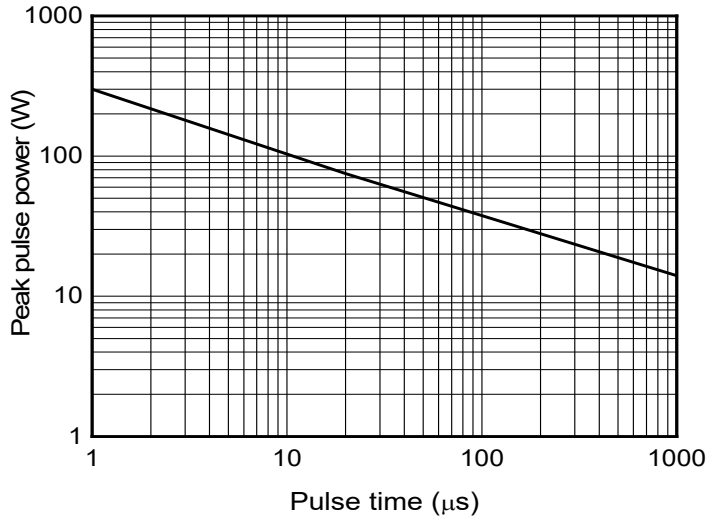
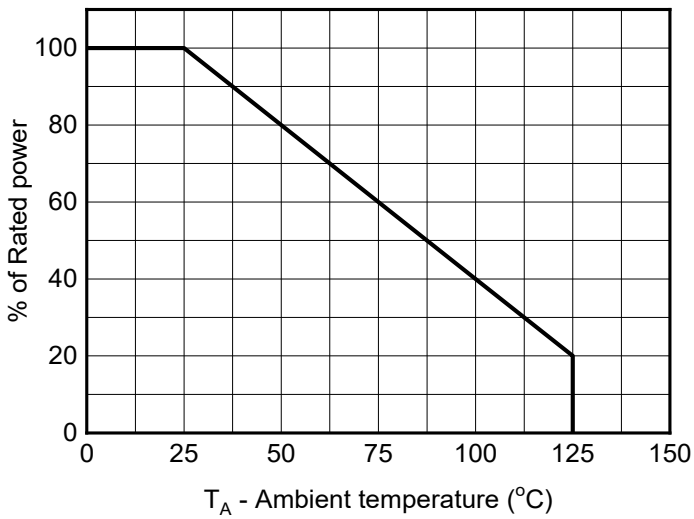
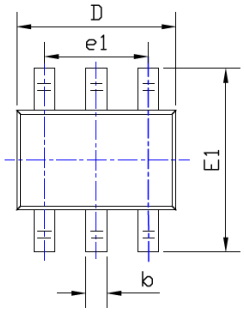


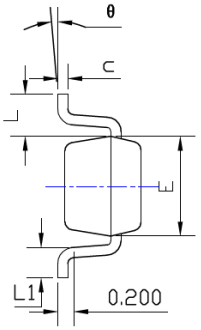
Fig.6 Power derating vs. Ambient temperature



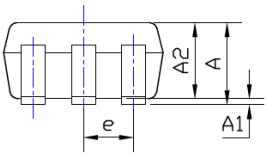
■ Outline Dimensions



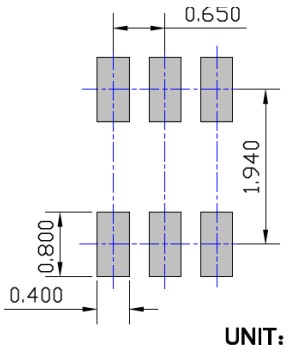
TOP VIEW



SIDE VIEW



SIDE VIEW



UNIT：mm

SUGGESTED SOLDER PAD LAYOUT

DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.043	0.900	1.100
A1	0.000	0.004	0.000	0.100
A2	0.035	0.039	0.900	1.000
b	0.006	0.014	0.150	0.350
c	0.004	0.010	0.100	0.250
D	0.071	0.087	1.800	2.200
E	0.045	0.053	1.150	1.350
E1	0.085	0.096	2.150	2.450
e	0.026TYP		0.650TYP	
e1	0.047	0.055	1.200	1.400
L	0.021REF		0.525REF	
L1	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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